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| FORM PTO-1449 (Colb) | ATTY DOCKET NO. 206,407 | SERIAL NUMBER 10/750,716 |
| LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS' INFORMATION STATEMENT | APPLICANT Yossi SHACHAM-DIAMAND et al. | EXAMINER AWA Klemanski |
|  | FILING DATE January 2, 2004 | GROUP ART UNIT 1742 1755 |

U.S. PATENT DOCUMENTS

| Examiner's Initials | | DOCUMENT NO. | DATE | NAME | CLASS | SUB | FILING DATE |
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| <i>AK</i> | AA | 5,695,810 | 12-1997 | Dubin, et al. | 438 | 643 | |
| <i>AK</i> | AB | 5,674,787 | 10-1997 | Zhao, et al. | 438 | 627 | |
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EXAMINER:

DATE CONSIDERED:

3-14-06

EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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